



Material Content Data Sheet



Halogen-Free

Sales Product Name	BFP 650F H6327	Issued	06. May 2021
MA#	MA001351748		
Package	PG-TSFP-4-1	Weight*	1.87 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.04		376	
	noble metal	gold	7440-57-5	0.003	0.15		1457	
	inorganic material	silicon	7440-21-3	0.024	1.28	1.47	12826	14659
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		79	
	non noble metal	titanium	7440-32-6	0.001	0.04		394	
	non noble metal	chromium	7440-47-3	0.002	0.12		1182	
	non noble metal	copper	7440-50-8	0.734	39.24	39.41	392435	394090
wire	noble metal	gold	7440-57-5	0.007	0.40	0.40	3957	3957
encapsulation	organic material	carbon black	1333-86-4	0.010	0.51		5130	
	plastics	epoxy resin	-	0.206	11.03		110298	
	inorganic material	silicondioxide	60676-86-0	0.744	39.75	51.29	397587	513015
leadfinish	non noble metal	tin	7440-31-5	0.049	2.62	2.62	26160	26160
plating	noble metal	silver	7440-22-4	0.090	4.81	4.81	48119	48119
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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